

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

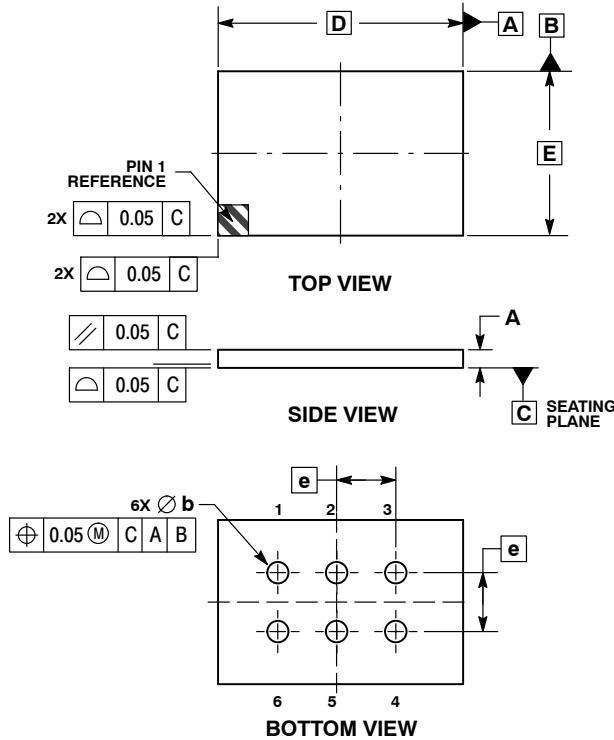
ON Semiconductor®



SCALE 4:1

WLCSP6 1.81x2.70 / EFCP2718-6CE-020
CASE 567HS
ISSUE A

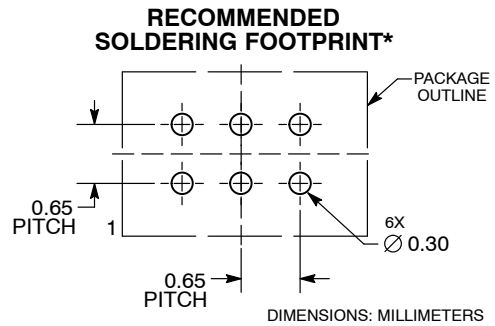
DATE 14 NOV 2014



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.18	0.22
b	0.27	0.33
D	2.70 BSC	
E	1.81 BSC	
e	0.65 BSC	



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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